

RF Components

Directional Couplers(For Dual Band) Shielded

HHM-23 Series

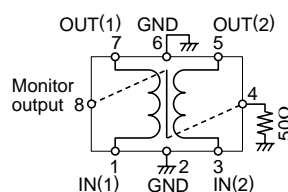
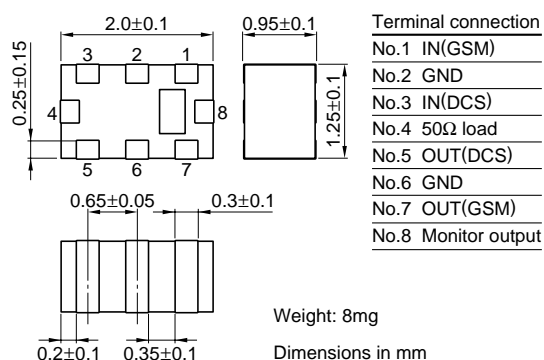
FEATURES

- Compact, thin, and lightweight chip coupler manufactured in ceramic sheet multilayering process (L2.0×W1.25×T0.95mm/8mg).
- Low loss and high isolation characteristics achieved in spite of smallest size.
- Provided with excellent environmental resistance and stable characteristics achieved under use of portable remote terminal in hostile environment.

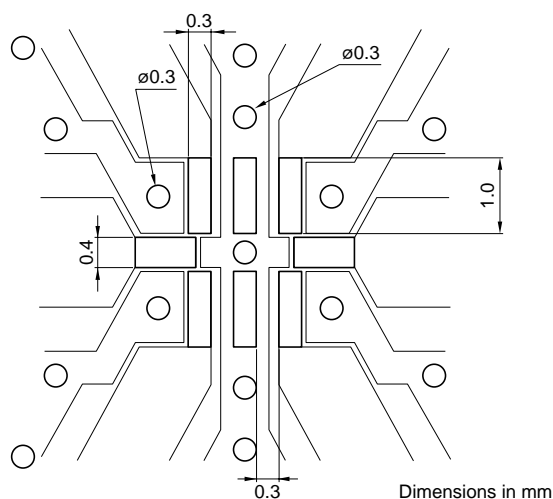
APPLICATIONS

Dual band digital cellular phone

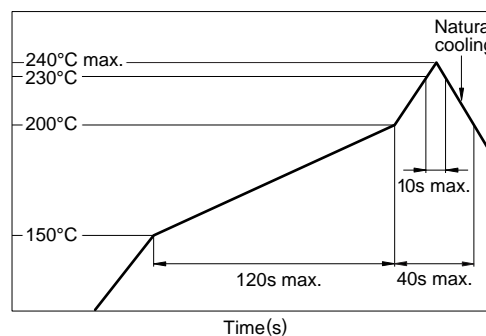
SHAPES AND DIMENSIONS/CIRCUIT DIAGRAM



RECOMMENDED PC BOARD PATTERN



RECOMMENDED REFLOW SOLDERING CONDITIONS



APPLICATIONS/TYPICAL ELECTRICAL CHARACTERISTICS

T_a=25±5°C

Part No.	Applications	Frequency f ₀ (MHz)	Insertion loss (dB)max.	Coupling factor (dB)typ.	I/O Isolation (dB)min.	VSWR max.
HHM2304	GSM/DCS Dual	880 to 915/1710 to 1785	0.3/0.45	-17.5/-15.5	25	1.5

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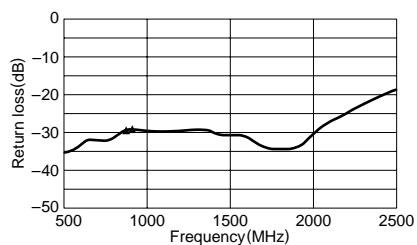
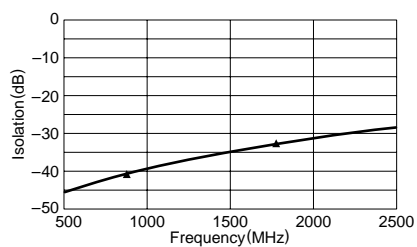
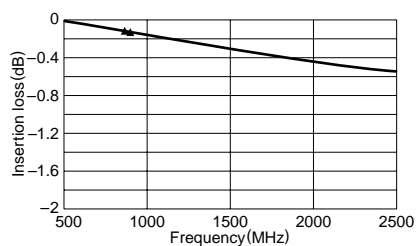
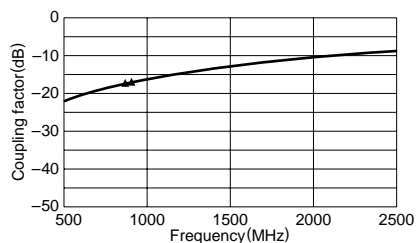
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TYPICAL ELECTRICAL CHARACTERISTICS

FREQUENCY CHARACTERISTICS

GSM HHM2304



DCS HHM2304

